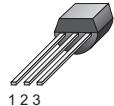


**HAOPIN MICROELECTRONICS CO.,LTD.**
**Description**

Glass passivated, sensitive gate thyristors in a plastic envelope, intended for use in general purpose switching and phase control applications. These devices are intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

Symbol	Simplified outline
	 <b>TO-92</b>
Pin	Description
1	Cathode
2	anode
3	gate
TAB	anode

**Applications:**

- ◆ Motor control
- ◆ Industrial and domestic lighting
- ◆ Heating
- ◆ Static switching

**Features**

- ◆ Blocking voltage to 400 V
- ◆ On-state RMS current to 0.8 A
- ◆ Ultra low gate trigger current

SYMBOL	PARAMETER	Value	Unit
$V_{DRM}$	Repetitive peak off-state voltages	400	V
$I_T \text{ (RMS)}$	RMS on-state current (full sine wave)	0.8	A
$I_{TSM}$	Non-repetitive peak on-state current (full cycle, $T_j$ initial=25°C)	8	A

SYMBOL	PARAMETER	Value	UNIT
$R_{th(j-a)}$	Junction to ambient (DC)	150	°C/W
$R_{th(j-l)}$	Junction to lead (DC)	80	°C/W



# XL0840

## SCRs

HAOPIN MICROELECTRONICS CO.,LTD.

Limiting values in accordance with the Maximum system(IEC 134)

SYMBOL	PARAMETER	CONDITIONS		Value	UNIT
$V_{DRM}$	Repetitive peak off-state Voltages		-	400	V
$I_{TSM}$	Non repetitive surge peak on-state current	Tp=8.3ms Tj=25°C Tp=10ms	-	8	A
			-	7	
$I_{T(AV)}$	Average On-state Current	Half Cycle=180° Tj=55°C	-	0.5	A
$I_{T(RMS)}$	RMS on-state current	Tj=55°C	-	0.8	A
$I_{GM}$	Peak gate current	Tp=20 μ s Tj=125°C	-	1	A
$dI/dt$	Critical rate of rise of on-state current	$I_G=2*I_{GT, tr}<=100ns$ $F=60Hz$	Tj=125°C	-	30 A/μ s
$P_{G(AV)}$	Average gate power		Tj=125°C	-	0.1 W
$I^2t$	$I^2t$ Value for fusing	Tp=10ms	Tj=25°C	-	0.24 A²s
$T_{stg}$ $T_j$	Average gate power dissipation Operating junction temperature range		-	-40 to +150 -40 to +125	°C

$T_j=25^\circ C$  unless otherwise stated

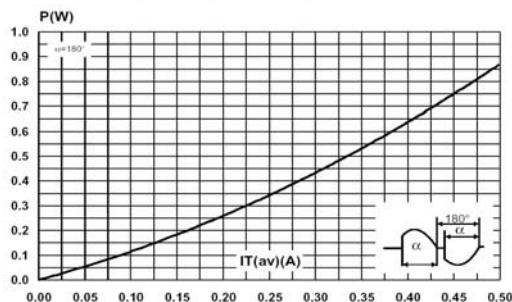
SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
Static characteristics						
$I_{GT}$ $V_{GT}$	Gate trigger current	$V_D=12V$ $R_L=140\Omega$	-	-	200	μ A
					0.8	V
$V_{TM}$ $V_{GD}$	Forward On- voltage	ITM=1.6A tp=380 μ s $Tj=25^\circ C$	-	-	1.95	V
		$V_D=V_{DRM}$ $R_L=3.3k\Omega$ $R_{GK}=1k\Omega$ $Tj=125^\circ C$	0.1	-	-	V
$I_H$ $I_L$	Holding Current	$I_T=50mA$ $R_{GK}=1k\Omega$	-	-	5	mA
		$I_G=1mA$ $R_{GK}=1k\Omega$	-	-	6	mA
$I_{DRM}$		$V_{DRM}$ $R_{GK}=1k\Omega$ $Tj=125^\circ C$ $Tj=25^\circ C$	-	-	100	μ A
$V_{TO}$	Threshold voltage				1.0	V

### Dynamic Characteristics

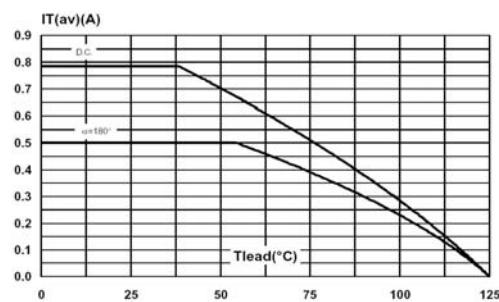
$Dv/dt$	Critical rate of rise of voltage rise	$V_D=67\% V_{DRM}$ $R_{GK}=1k\Omega$ $Tj=125^\circ C$	75	-	-	$V/\mu s$
$t_{gd}$	Gate controlled delay time	$I_G=10mA$ , $dI_g/dt=0.1A/\mu s$	-	-	-	μs
$t_g$	commutated turn-off time	$V_D=0.67V_{DRM}$ , $Tj=85^\circ C$ $IT=IT(AV)$ , $V_R=35V$	-	-	-	μs

**HAOPIN MICROELECTRONICS CO.,LTD.**
**Description**

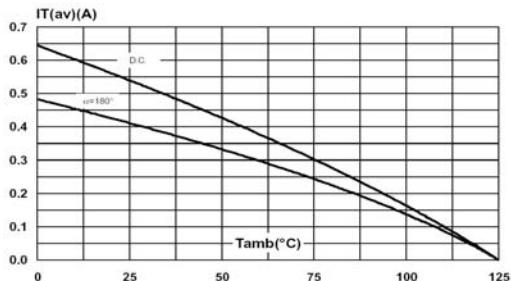
**Fig. 1:** Maximum average power dissipation versus average on-state current.



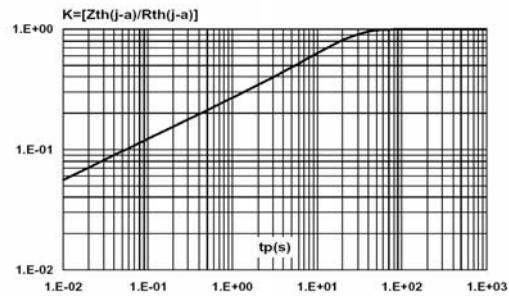
**Fig. 2-1:** Average and D.C. on-state current versus lead temperature.



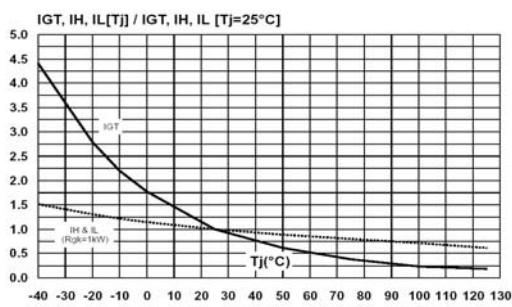
**Fig. 2-2:** Average and D.C. on-state current versus ambient temperature (device mounted on FR4 with recommended pad layout).



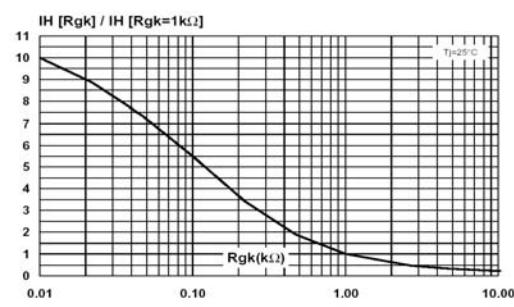
**Fig. 3:** Relative variation of thermal impedance junction to ambient versus pulse duration.



**Fig. 4:** Relative variation of gate trigger current, holding current and latching current versus junction temperature (typical values).

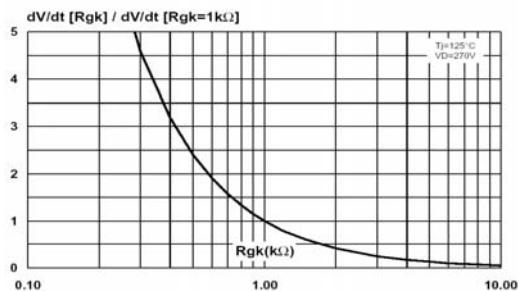


**Fig. 5:** Relative variation of holding current versus gate-cathode resistance (typical values).

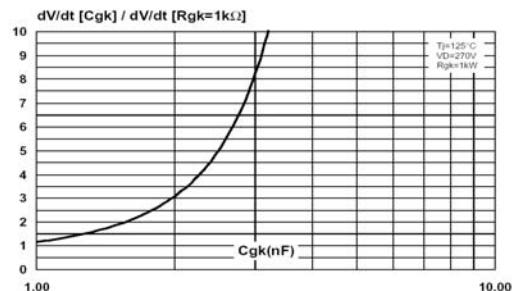


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**Description**

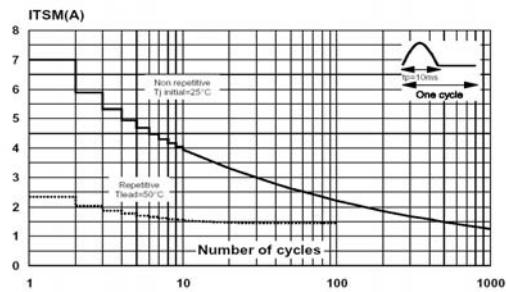
**Fig. 6:** Relative variation of dV/dt immunity versus gate-cathode resistance (typical values).



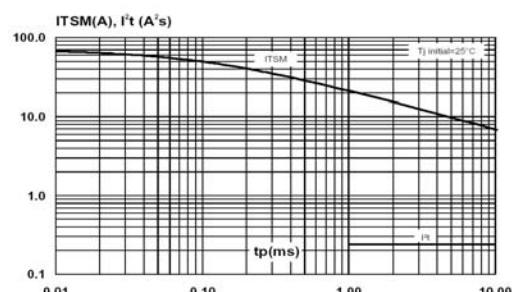
**Fig. 7:** Relative variation of dV/dt immunity versus gate-cathode capacitance (typical values).



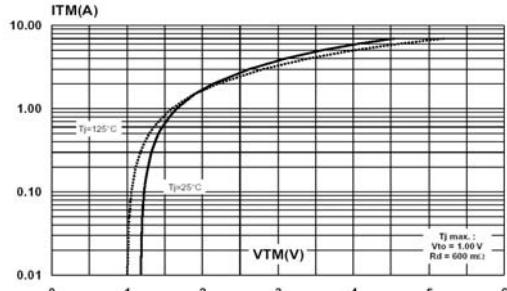
**Fig. 8:** Surge peak on-state current versus number of cycles.



**Fig. 9:** Non repetitive surge peak on-state current for a sinusoidal pulse with width tp<10ms, and corresponding value of I<sup>2</sup>t.



**Fig. 10:** On-state characteristics (maximum values).



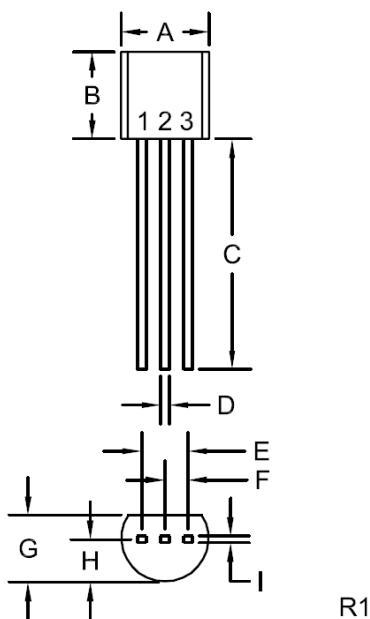
## HAOPIN MICROELECTRONICS CO.,LTD.

## MECHANICAL DATA

Dimensions in mm

Net Mass: 0.2 g

TO-92



SYMBOL	DIMENSIONS			
	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A (DIA)	0.175	0.205	4.45	5.21
B	0.170	0.210	4.32	5.33
C	0.500	-	12.70	-
D	0.016	0.022	0.41	0.56
E	0.100		2.54	
F	0.050		1.27	
G	0.125	0.165	3.18	4.19
H	0.080	0.105	2.03	2.67
I	0.015		0.38	

TO-92 (REV: R1)

R1